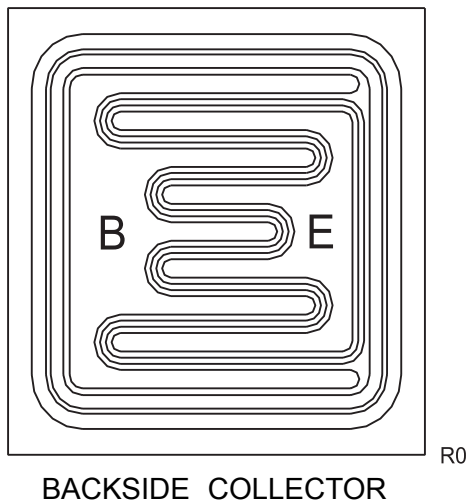


PROCESS DETAILS

Process	EPITAXIAL BASE
Die Size	66 X 66 MILS
Die Thickness	12.5 ± 1.0 MILS
Base Bonding Pad Area	12 X 24 MILS
Emitter Bonding Pad Area	11 X 14 MILS
Top Side Metalization	Al - 50,000Å
Back Side Metalization	Cr/Ni/Ag - 16,000Å

GEOMETRY**GROSS DIE PER 4 INCH WAFER**

2,630

PRINCIPAL DEVICE TYPES

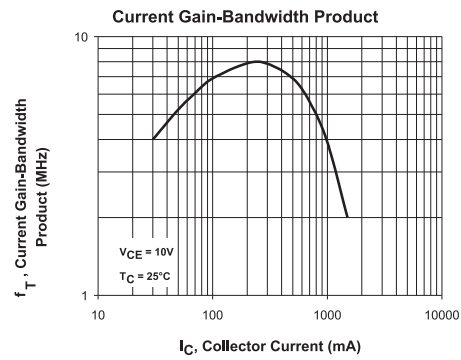
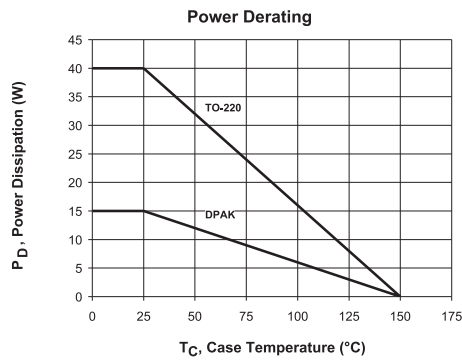
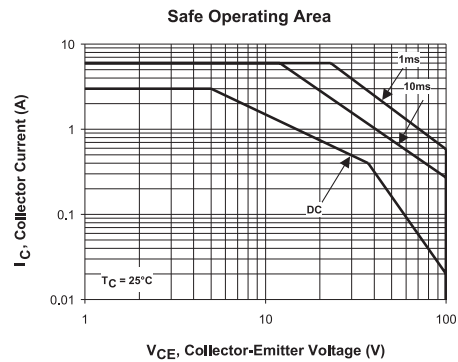
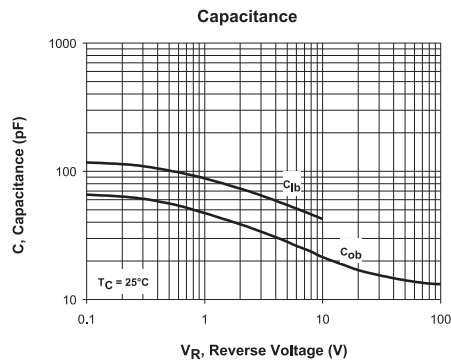
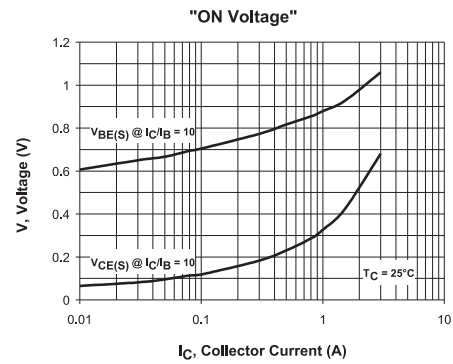
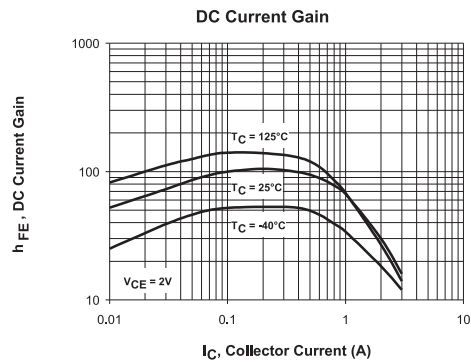
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